

FDP8N50NZ / FDPF8N50NZ N-Channel UniFET™ II MOSFET 500 V, 8 A, 850 mΩ

Features

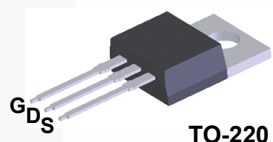
- $R_{DS(on)} = 770\text{ m}\Omega$ (Typ.) @ $V_{GS} = 10\text{ V}$, $I_D = 4\text{ A}$
- Low Gate Charge (Typ. 14 nC)
- Low C_{rss} (Typ. 5 pF)
- 100% Avalanche Tested
- Improve dv/dt Capability
- ESD Improved Capability
- RoHS Compliant

Applications

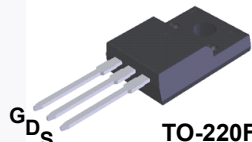
- LCD/LED TV
- Lighting
- Uninterruptible Power Supply
- AC-DC Power Supply

Description

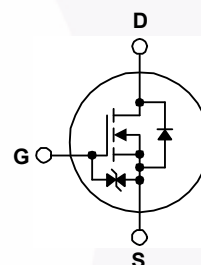
UniFET™ II MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on advanced planar stripe and DMOS technology. This advanced MOSFET family has the smallest on-state resistance among the planar MOSFET, and also provides superior switching performance and higher avalanche energy strength. In addition, internal gate-source ESD diode allows UniFET II MOSFET to withstand over 2kV HBM surge stress. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.



TO-220



TO-220F



MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted*

Symbol	Parameter	FDP8N50NZ	FDPF8N50NZ	Unit
V_{DSS}	Drain to Source Voltage	500		V
V_{GSS}	Gate to Source Voltage	± 25		V
I_D	Drain Current	- Continuous ($T_C = 25^\circ\text{C}$)	8	A
		- Continuous ($T_C = 100^\circ\text{C}$)	4.8	
I_{DM}	Drain Current	- Pulsed (Note 1)	32	A
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	122	mJ
I_{AR}	Avalanche Current	(Note 1)	8	A
E_{AR}	Repetitive Avalanche Energy	(Note 1)	13	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	10	V/ns
P_D	Power Dissipation	($T_C = 25^\circ\text{C}$)	130	W
		- Derate above 25°C	1	
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to $+150$		$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300		$^\circ\text{C}$

*Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FDP8N50NZ	FDPF8N50NZ	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.96	3.1	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	62.5	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP8N50NZ	FDP8N50NZ	TO-220	Tube	N/A	50 units
FDPF8N50NZ	FDPF8N50NZ	TO-220F	Tube	N/A	50 units

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$, $T_C = 25^\circ\text{C}$	500	-	-	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, Referenced to 25°C	-	0.5	-	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 500\text{V}$, $V_{GS} = 0\text{V}$ $V_{DS} = 400\text{V}$, $T_C = 125^\circ\text{C}$	-	-	1 10	μA
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 25\text{V}$, $V_{DS} = 0\text{V}$	-	-	± 10	μA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250\mu\text{A}$	3.0	-	5.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}$, $I_D = 4\text{A}$	-	0.77	0.85	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 20\text{V}$, $I_D = 4\text{A}$	-	6.3	-	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{V}$, $V_{GS} = 0\text{V}$ $f = 1\text{MHz}$	-	565	735	pF
C_{oss}	Output Capacitance		-	80	105	pF
C_{rss}	Reverse Transfer Capacitance		-	5	8	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{DS} = 400\text{V}$, $I_D = 8\text{A}$ $V_{GS} = 10\text{V}$ (Note 4)	-	14	18	nC
Q_{gs}	Gate to Source Gate Charge		-	4	-	nC
Q_{gd}	Gate to Drain "Miller" Charge		-	6	-	nC

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 250\text{V}$, $I_D = 8\text{A}$ $R_G = 25\Omega$, $V_{GS} = 10\text{V}$ (Note 4)	-	17	45	ns
t_r	Turn-On Rise Time		-	34	80	ns
$t_{d(off)}$	Turn-Off Delay Time		-	43	95	ns
t_f	Turn-Off Fall Time		-	27	60	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	8	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	30	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _{SD} = 8A	-	-	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _{SD} = 8A	-	228	-	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100A/μs	-	1.43	-	μC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $L = 3.8\text{mH}$, $I_{AS} = 8\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 8\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Characteristics

Figure 1. On-Region Characteristics

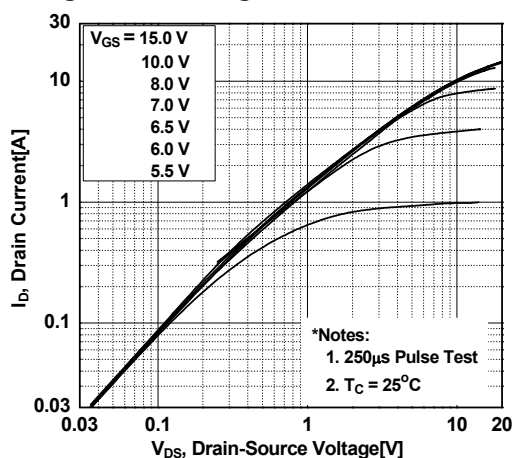


Figure 2. Transfer Characteristics

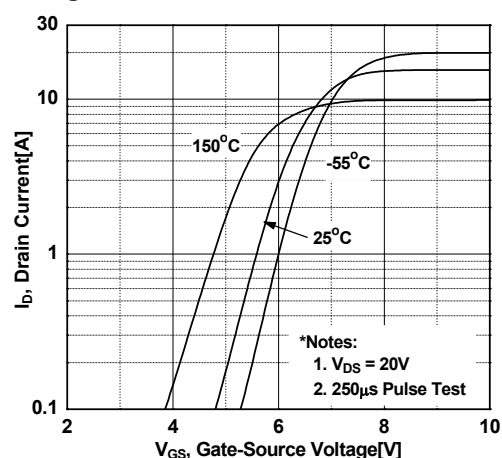


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

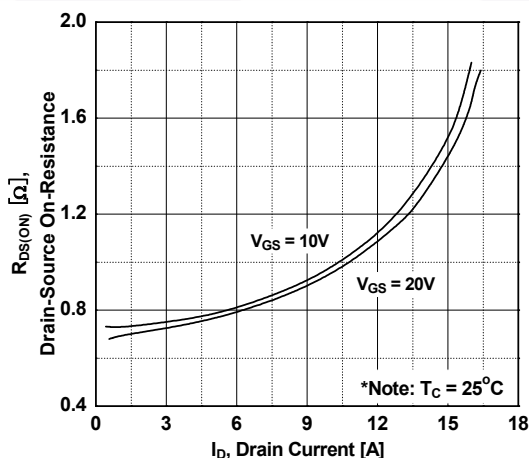


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

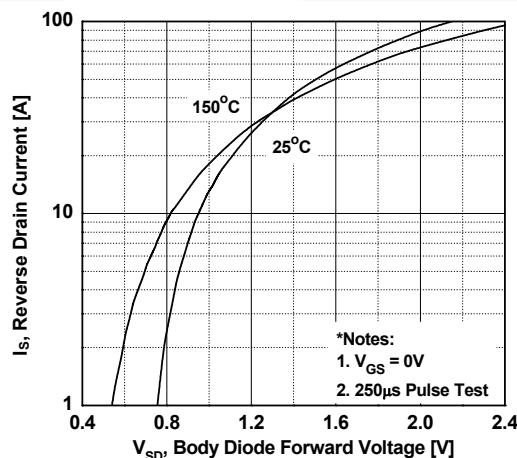


Figure 5. Capacitance Characteristics

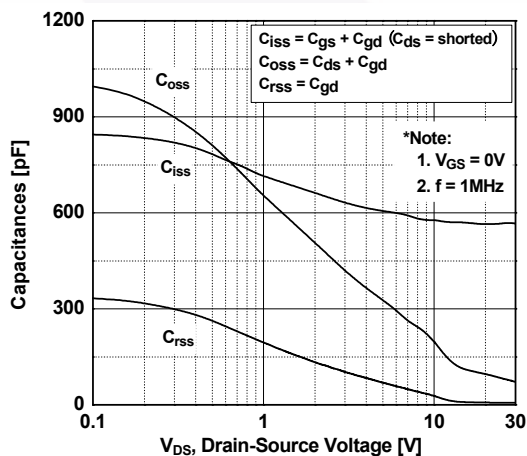
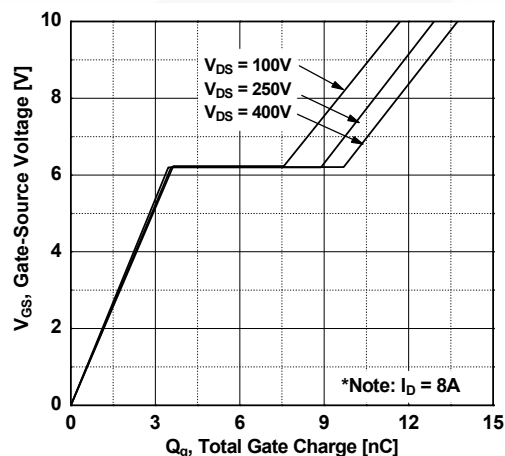


Figure 6. Gate Charge Characteristics



Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

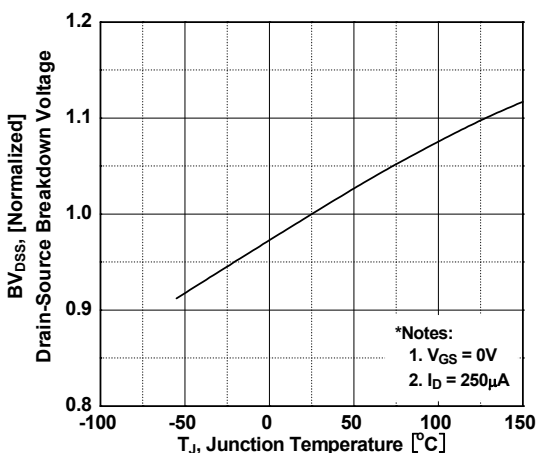


Figure 8. On-Resistance Variation vs. Temperature

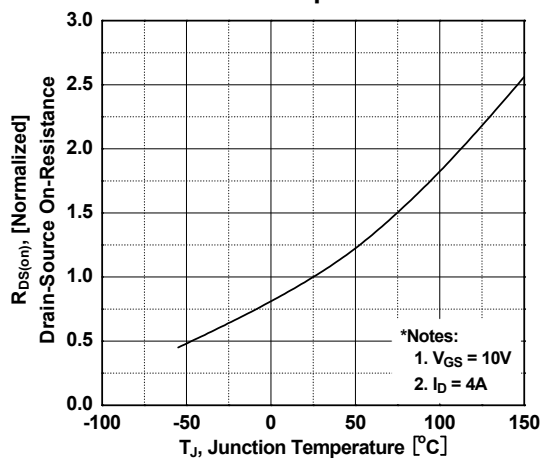


Figure 9. Maximum Safe Operating Area - FDP8N50NZ

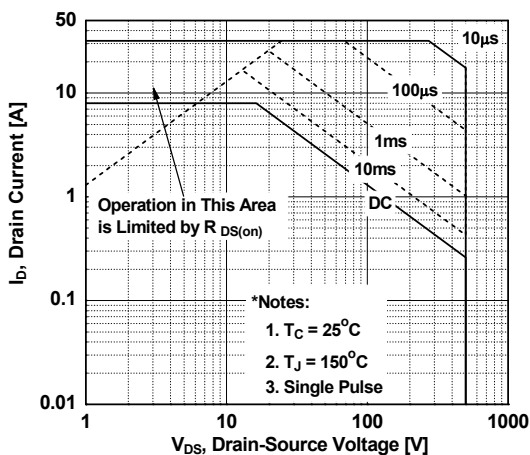


Figure 10. Maximum Safe Operating Area - FDPF8N50NZ

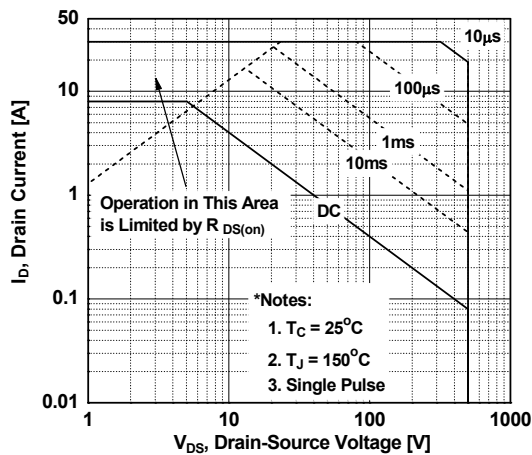


Figure 11. Maximum Drain Current vs. Case Temperature

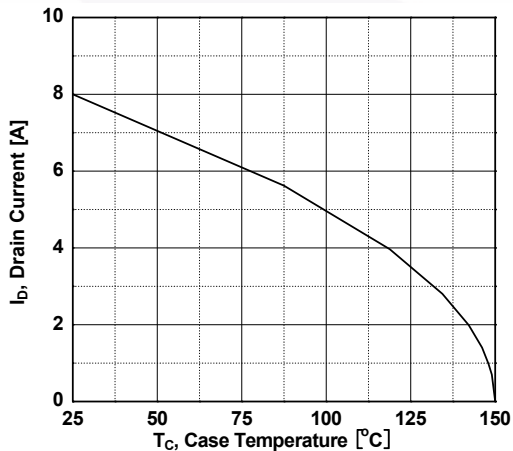
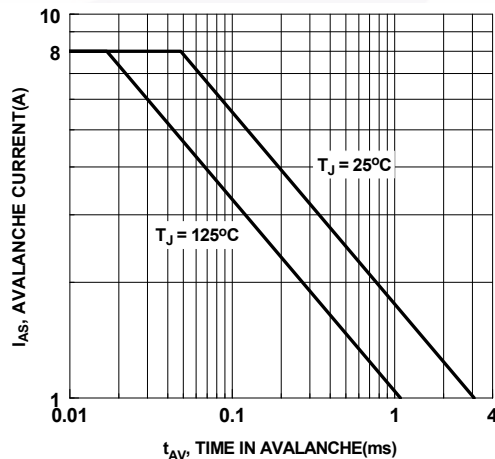


Figure 12. Unclamped Inductive Switching Capability



Typical Characteristics (Continued)

Figure 13. Transient Thermal Response Curve - FDP8N50NZ

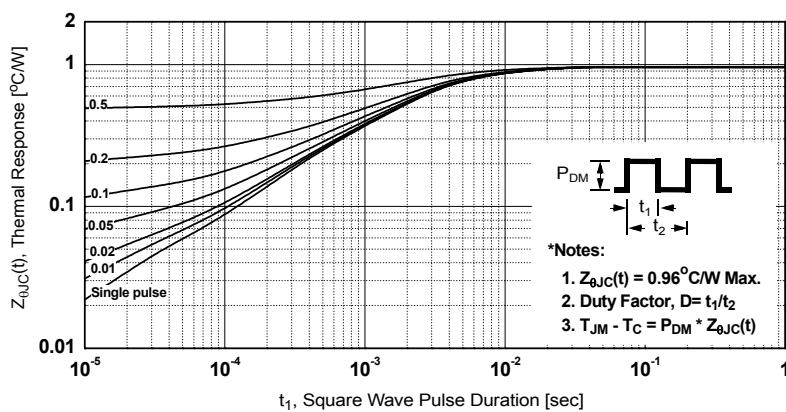


Figure 14. Transient Thermal Response Curve - FDPF8N50NZ

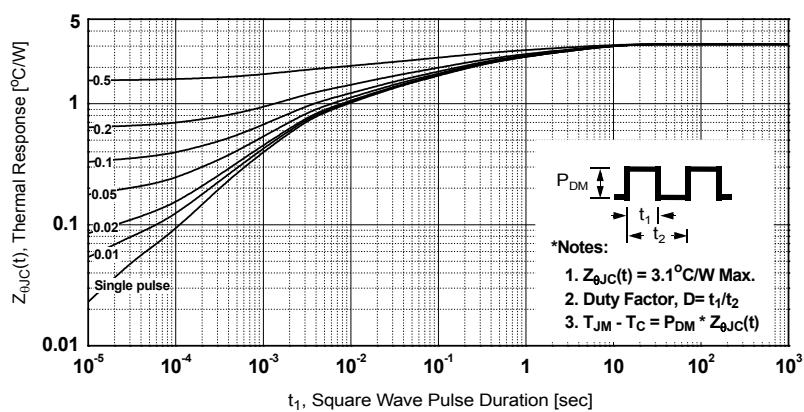


Figure 15. Gate Charge Test Circuit & Waveform

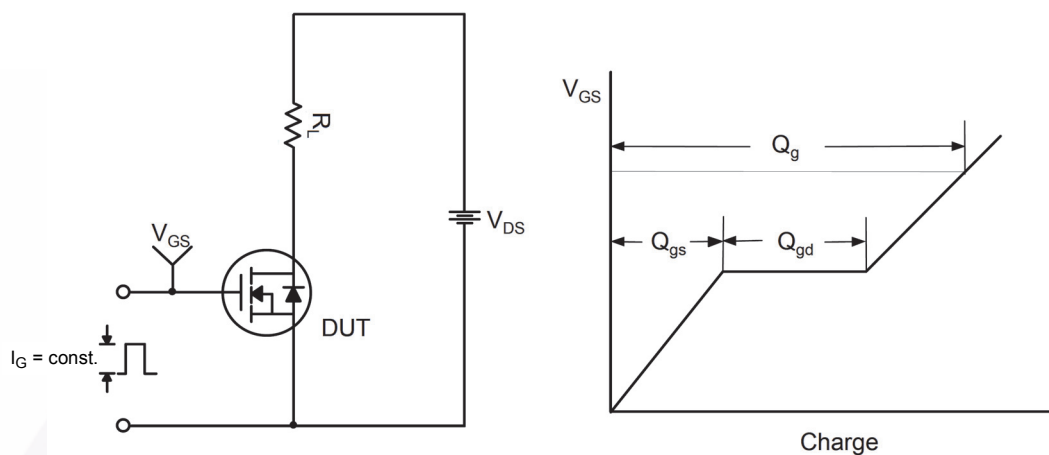


Figure 16. Resistive Switching Test Circuit & Waveforms

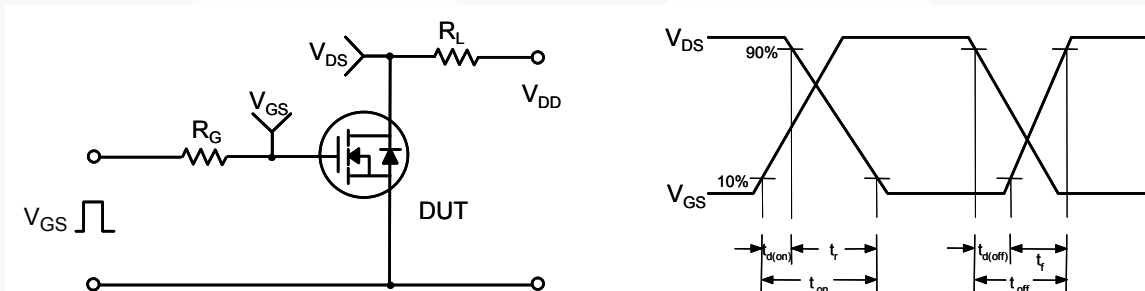


Figure 17. Unclamped Inductive Switching Test Circuit & Waveforms

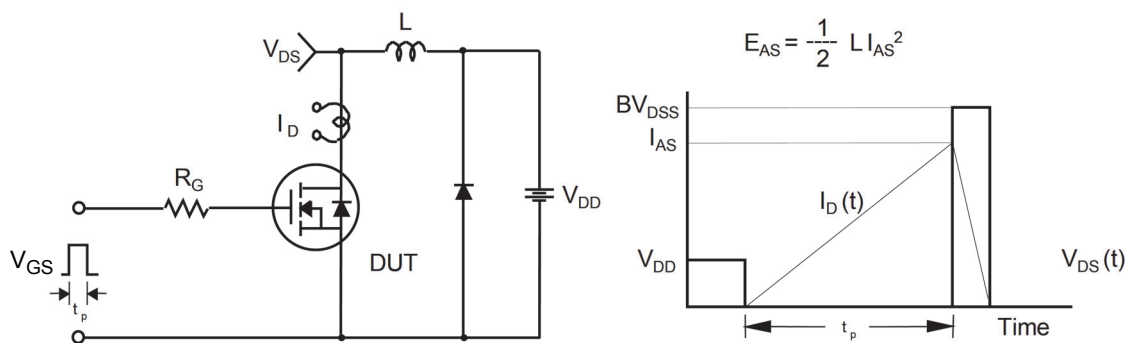
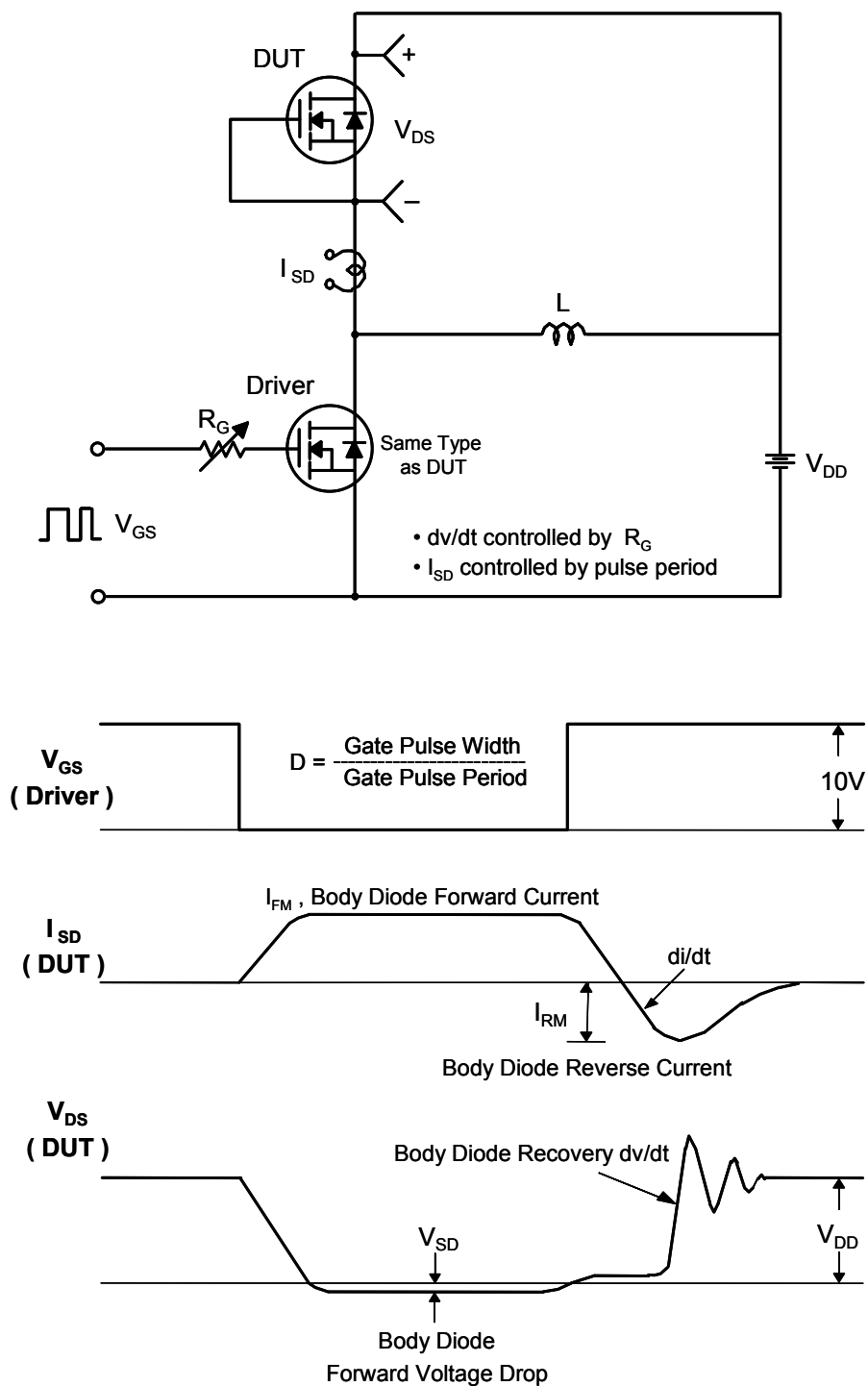


Figure 18. Peak Diode Recovery dv/dt Test Circuit & Waveforms



Mechanical Dimensions

TO-220 3L

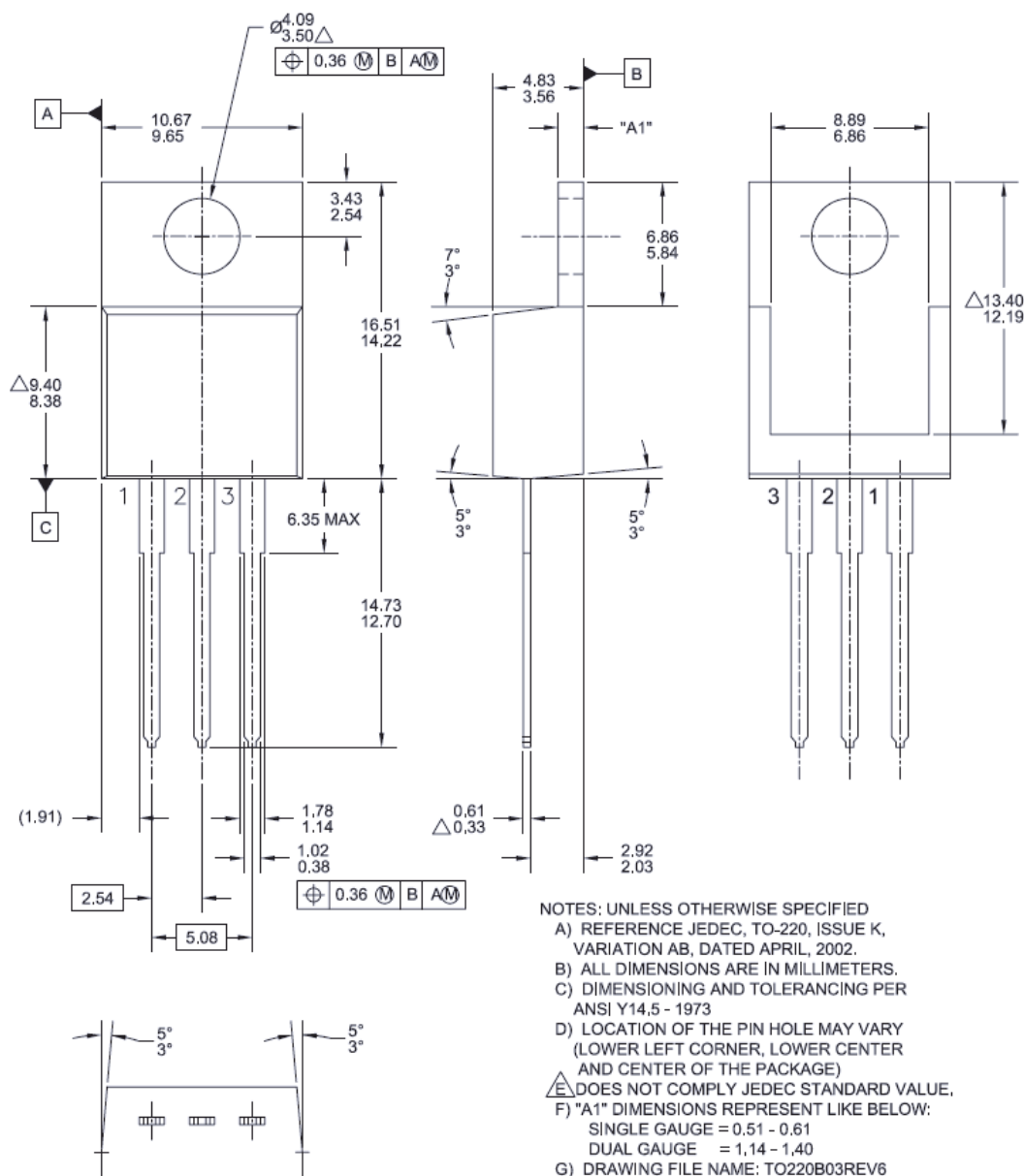


Figure 19. TO-220, Molded, 3Lead, Jedec Variation AB

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Dimension in Millimeters

Mechanical Dimensions

TO-220F 3L

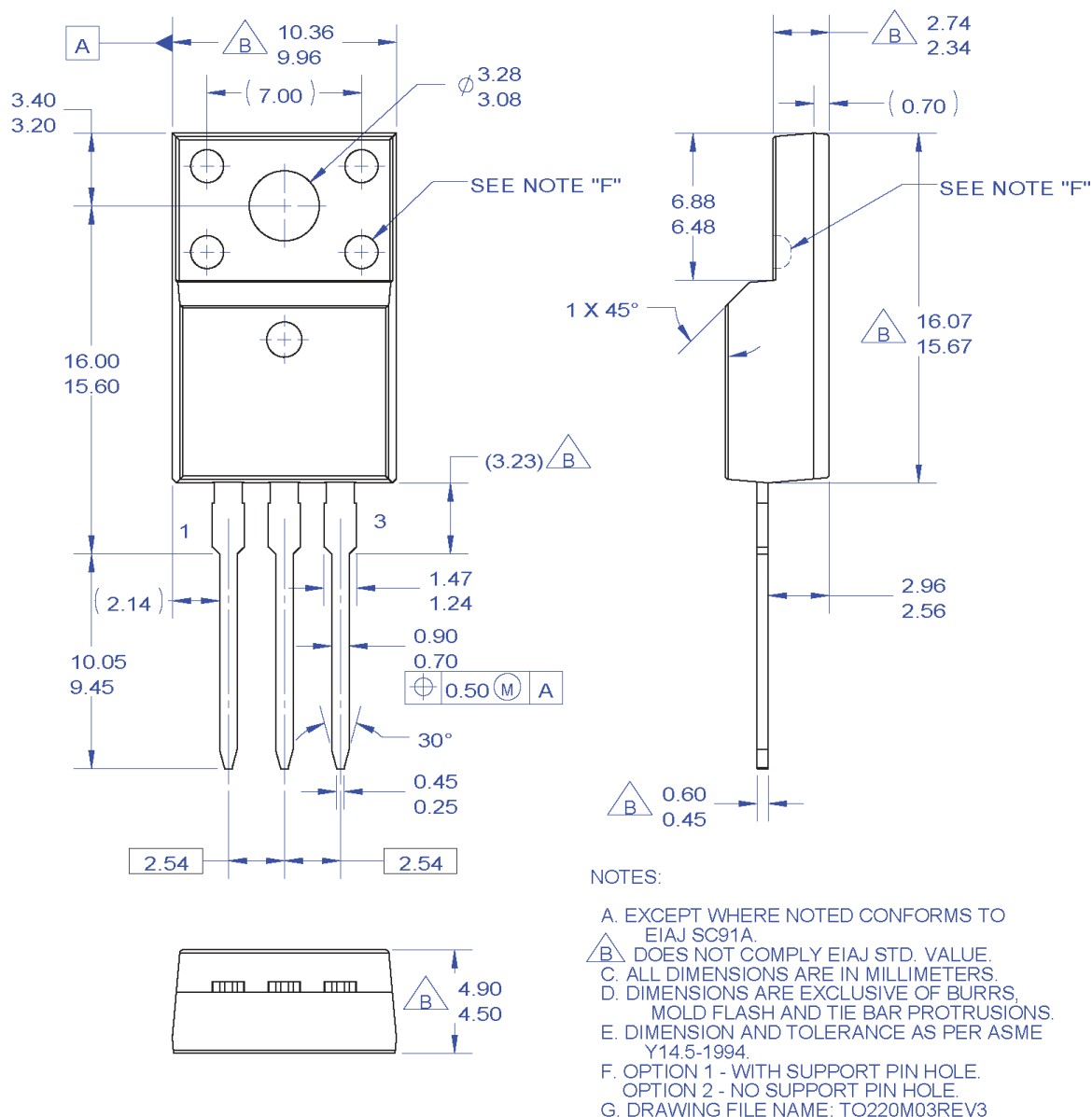


Figure 20. TO220, Molded, 3LD, Full Pack, EIAJ SC91, Straight Lead

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Dimension in Millimeters



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